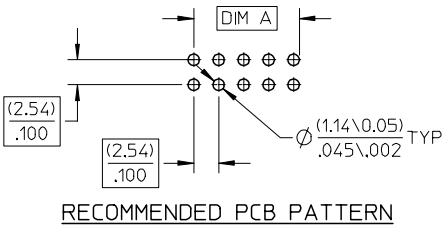
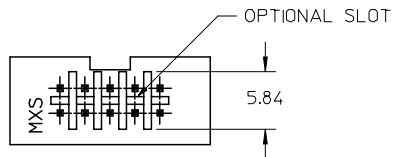
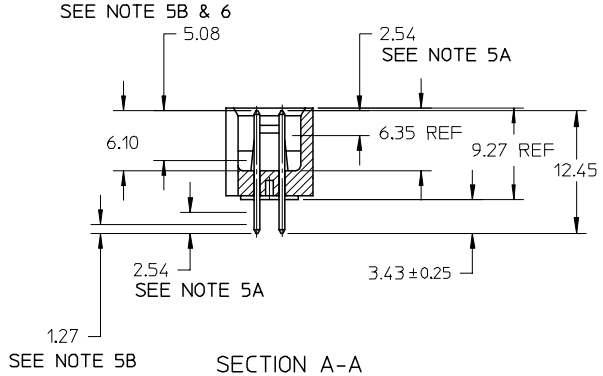
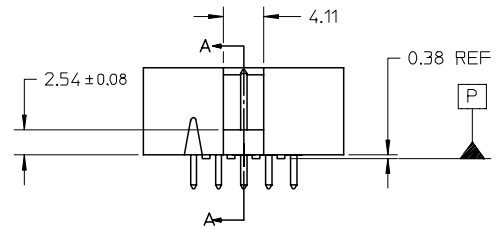
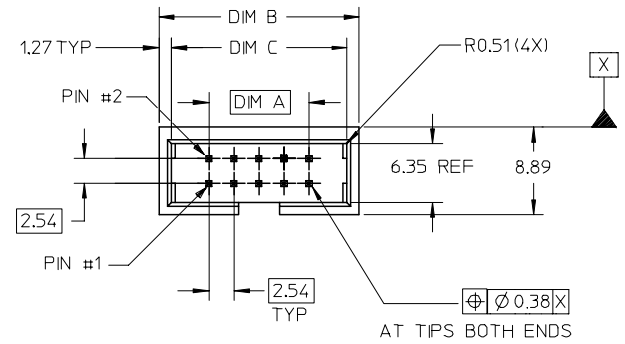


10 9 8 7 6 5 4 3 2 1

PART NUMBER	CKT SIZE	VOIDED PIN LOCATION	DIM A	DIM B	DIM C
87834-0643	06	2	5.08	15.24	12.70
87834-0843	08	1	7.62	17.78	15.24
87834-5043	50	25	60.96	71.12	68.58
87834-2643	26	26	30.48	40.64	38.10



**NOTES :**

- MATERIAL :  
HOUSING: NYLON (PA), UL94V-0, COLOR: NATURAL.  
PIN: COPPER ALLOY.
- PIN PUSHOUT FORCE 0.91 KG MIN.
- PIN SOLDERABILITY PER MOLEX SPEC. ES-152.
- WAFER TO BE FLAT WITHIN 0.03MM/CM
- DIMENSIONS FOR PLATING LOCATIONS : A - MEASURE POINT FOR THICKNESS.  
B - MINIMUM COVERAGE.
- GOLD END OF PIN UNLESS OVERALL PLATED.
- FINISH :  
0.38um MIN GOLD AND 2.54um MIN TIN  
IN SELECTED AREA OVER 1.27um MIN. NICKEL.
- FOR ILLUSTRATION PURPOSE A 10 CKT IS SHOWN.
- PRODUCT SPECIFICATION PS-70246-100 APPLIES.

ADD PART NUMBER	2005/06/27
EC NO: S2005-1018	2005/06/27
DRWN:KELIM	2005/06/27
CHKD:C@BYNN	2005/06/27
APPR:PTLIM	2005/06/27

REV	DESCRIPTION
A2	

QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	
	mm	INCH
▽=0	4 PLACES ± ---	± ---
▽=0	3 PLACES ± ---	± ---
	2 PLACES ± 0.20	± ---
	1 PLACE ± ---	± ---
	ANGULAR ± 3 °	
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	

DIMENSION STYLE		SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
MM ONLY		NTS	METRIC	
DRAWN BY	DATE	TITLE	C-GRID, SHROUDED WAFER SLOTTED, WITH VOID NO END WINDOW & PEG	
RSHAN	2003/11/20			
CHECKED BY	DATE			
KCLING	2003/12/05		MOLEX INCORPORATED	
APPROVED BY	DATE			
SKTOH	2003/12/06			
MATERIAL NO.	DOCUMENT NO.	SHEET NO.		
	SD-87834-019	1 OF 1		
SIZE	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			
A3				

9 8 7 6 5 4 3 2 1